

10.5.00

11-15-2000



To the Honorable Commissioner of Patents and Trademarks
Please record the attached original documents

101517405

BOX ASSIGNMENTS

1. Name of conveying party(ies):
(1) Akira YAZAWA (3) Nozomu HASEGAWA
(2) Yoichi TAKEDA (4) Yoshiaki MORI

2. Name and address of receiving party(ies):
Name: (1) SUMITOMO METAL MINING CO., LTD.
(2) MITSUBISHI MATERIALS CORPORATION

Additional name(s) of conveying party(ies) attached? Yes No

Internal Address:

3. Nature of conveyance:

Street Address: (1) 5-11-3 Shimbashi, Minato-ku,
Tokyo 105-0004, Japan
(2) 1-5-1 Otemachi, Chiyoda-ku,
Tokyo 100-8222, Japan

Assignment Merger
 Security Agreement Change of Name

City:

State: Zip Code:

Other

Additional name(s) & Address(es) attached?

Execution Date: (1) June 20, 2000, (2) June 23, 2000, (3) August 2,
2000 and (4) July 28, 2000

Yes No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application:

A. Patent Application Number(s):

B. Patent Number(s):

09/555,020

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

6. Total number of applications and registrations involved:
1

Name: Mr. Ernest F. Chapman

7. Total fee (37 CFR 3.41): \$40

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT
& DUNNER, L.L.P.

Enclosed (Please charge deficiency to deposit account)

Authorized to be charged to deposit account

Street Address: 1300 I Street, N.W.

8. Deposit account number: 06-0916

City: Washington

State: DC Zip: 20005-3315

9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David W. Hill

October 5, 2000

Signature

Date

Total number of pages including cover sheet, attachments and documents: 2

A S S I G N M E N T

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

Method of Smelting Copper Sulfide Concentrate
for which I/WE executed an application for United States Letters Patent concurrently herewith or on _____ or filed an application for United States Letters Patent on _____, 19____ (Serial No. _____); and

WHEREAS, SUMITOMO METAL MINING CO., LTD. and MITSUBISHI
MATERIALS CORPORATION

a corporation of Tokyo, Japan, whose post office address is 5-11-3 Shimbashi, Minato-ku, Tokyo 105-0004, Japan and
1-5-1 Otemachi, Chiyoda-ku, Tokyo 100-8222, Japan

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 09/555,020, filed May 23, 2000) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

1. Full Name of Sole or First Assignor	: Assignor's Signature	: Date
<u>Akira YAZAWA</u>	: <u>A. Yazawa</u>	: <u>20 June 2000</u>
Address	: <u>16-32 Niizakamachi, Aoba-ku, Sendai-shi,</u>	: Citizenship
	<u>Miyagi 981-0934 Japan</u>	: Japan
2. Full Name of Second Assignor	: Assignor's Signature	: Date
<u>Yoichi TAKEDA</u>	: <u>Yoichi Takeda</u>	: <u>23 June, 2000</u>
Address	: <u>4-3-5 Ueda, Morioka-shi, Iwate</u>	: Citizenship
	<u>020-0066 Japan</u>	: Japan
3. Full Name of Third Assignor	: Assignor's Signature	: Date
<u>Nozomu HASAGAWA</u>	: <u>N. Hasagawa</u>	: <u>2 August, 2000</u>
Address	: <u>1-3-25 Koishikawa, Bunkyo-ku, Tokyo</u>	: citizenship
	<u>112-0002 Japan</u>	: Japan

4. Full Name of Fourth Assignor	: Assignor's Signature	: Date
Yoshiaki MORI	: <i>Yoshi Mori</i>	: 28 July, 2000
Address 2-25 Shinsei-cho, Hyuga-shi, Miyazaki		: citizenship
883-0013 Japan		: Japan
5. Full Name of Fifth Assignor	: Assignor's Signature	: Date
Address		: citizenship
6. Full Name of Sixth Assignor	: Assignor's Signature	: Date
Address		: citizenship
7. Full Name of Seventh Assignor	: Assignor's Signature	: Date
Address		: citizenship
8. Full Name of Eighth Assignor	: Assignor's Signature	: Date
Address		: citizenship
9. Full Name of Ninth Assignor	: Assignor's Signature	: Date
Address		: citizenship
10. Full Name of Tenth Assignor	: Assignor's Signature	: Date
Address		: citizenship
11. Full Name of Eleventh Assignor	: Assignor's Signature	: Date
Address		: citizenship
12. Full Name of Twelfth Assignor	: Assignor's Signature	: Date
Address		: citizenship